



2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

Δ	D	DI		C	Δ	TI	n	NS	•
_		_	_	•	_		u		

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.027g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	2	Α		
V_{RRM}	200 - 1000	V		
I _{FSM}	50	Α		
T _{J MAX}	150	°C		
Package	SOD-12	.8		
Configuration	Single d	ie		





SOD-128



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2D FSH	RS2G FSH	RS2J FSH	RS2K FSH	RS2M FSH	UNIT
Marking code on the device			RS2DFH	RS2GFH	RS2JFH	RS2KFH	RS2MFH	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		I _F	2				Α	
Surge peak forward current, single half sine-wave superimposed on rated load $t = 1.0 \text{ms}$			50					А
		I _{FSM}	140					Α
Junction temperature		T _J	-55 to +150			°C		
Storage temperature		T _{STG}	-55 to +150				°C	

Taiwan Semiconductor

THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W			
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	73	°C/W			
Junction-to-case thermal resistance	$R_{\Theta JC}$	14	°C/W			

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETI	ER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 1A, T _J = 25°C		0.93	-	V
	RS2DFSH RS2GFSH RS2JFSH	I _F = 2A, T _J = 25°C		1.01	1.30	V
		I _F = 1A, T _J = 125°C		0.78	-	V
F (1)		I _F = 2A, T _J = 125°C		0.88	1.02	V
Forward voltage ⁽¹⁾		I _F = 1A, T _J = 25°C	V _F	0.98	-	V
	RS2KFSH RS2MFSH	I _F = 2A, T _J = 25°C		1.06	1.30	V
		I _F = 1A, T _J = 125°C		0.83	-	V
		I _F = 2A, T _J = 125°C		0.93	1.05	V
D	(2)	T _J = 25°C	- I _R	-	1	μA
Reverse current @ rated V _R ⁽	,	T _J = 125°C		-	40	μΑ
	RS2DFSH RS2GFSH		t _{rr}	-	150	ns
Reverse recovery time	RS2JFSH	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$		-	250	ns
	RS2KFSH RS2MFSH	- III - 0.20/ (-	500	ns
Junction capacitance	RS2DFSH RS2GFSH RS2JFSH	1MHz, V _R = 4.0V	CJ	11	-	pF
	RS2KFSH RS2MFSH	, , ,		10	-	pF

Notes:

- (1) Pulse test with PW = 0.3ms
- (2) Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
RS2xFSH	SOD-128	14,000 / Tape & Reel			

Notes:

(1) "x" defines voltage from 200V(RS2DFSH) to 1000V(RS2MFSH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

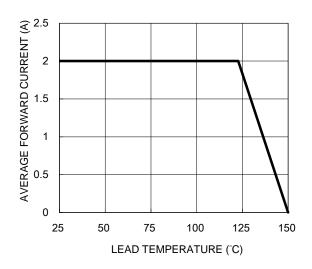


Fig.3 Typical Reverse Characteristics

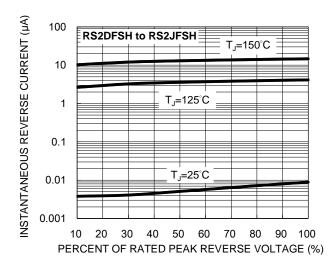


Fig.5 Typical Reverse Characteristics

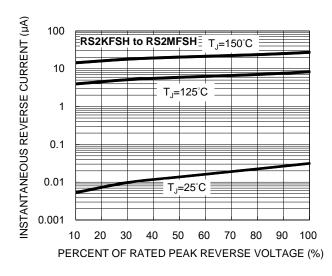


Fig.2 Typical Junction Capacitance

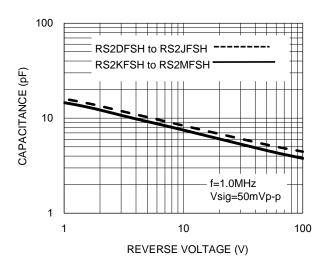


Fig.4 Typical Forward Characteristics

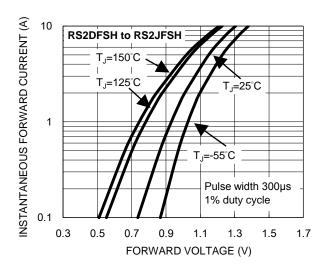
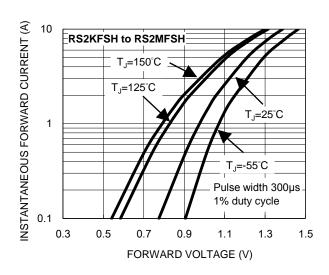


Fig.6 Typical Forward Characteristics

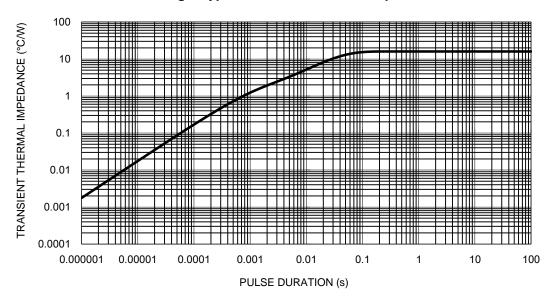




CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

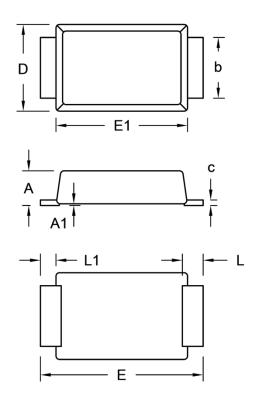
Fig.7 Typical Transient Thermal Impedance



Taiwan Semiconductor

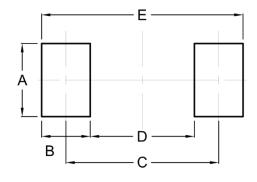
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM.	Unit	(mm)	Unit (inch)		
DIN.	Min.	Max.	Min.	Max.	
Α	0.90	1.10	0.035	0.043	
A1	0.00	0.10	0.000	0.004	
b	1.60	1.90	0.063	0.075	
С	0.10	0.22	0.004	0.009	
D	2.30	2.70	0.091	0.106	
E	4.40	5.00	0.173	0.197	
E1	3.60	4.00	0.142	0.157	
L	0.40	0.80	0.016	0.031	
L1	0.30	0.60	0.012	0.024	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.